PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Martin LIU	03/11/2010
Richard CHU	03/11/2010
Hung-Hua LIN	03/11/2010
H.T. HUANG	03/11/2010
Jung-Huei PENG	03/11/2010
Yuan-Chih HSIEH	03/16/2010
Lan-Lin CHAO	03/11/2010
Chun-Wen CHENG	03/16/2010
Chia-Shiung TSAI	03/16/2010

RECEIVING PARTY DATA

Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

CH $40.00 12729911

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12729911

CORRESPONDENCE DATA

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Docket No.: 2009-0859 / 24061.1422
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

(1)	Martin Liu	of	3F, No. 7, Bao-an Road Yonghe City, Taipei County 234, Taiwan, R.O.C.
(2)	Richard Chu	of	4F., NO. 9-2, Ln. 110, Qiangang st., shilin Dist., ~~Taipei City 11~~, Taiwan, R.O.C.
(3)	Hung-Hua Lin	of	1F, No. 22, Alley 3, Lane 128, Jinghua Street Wenshan District Taipei City 116, Taiwan, R.O.C.
(4)	H. T. Huang	of	No. 4, Xiwei Neighborhood 2, Bailu Vil Bade City, Taoyuan County 33455, Taiwan, R.O.C.
(5)	Jung-Huei Peng	of	7F-1, No. 6, Zihciang 6th Street Jhubei City, Hsinchu Hsien, Taiwan, R.O.C.
(6)	Yuan-Chih Hsieh	of	4F, No. 12, Lane 1007, Daxue Road Hsin-Chu City 300, Taiwan, R.O.C.
(7)	Lan-Lin Chao	of	3F, No. 113, Zihli Street Sindian City, Taipei County, Taiwan, R.O.C.
(8)	Chun-Wen Cheng	of	No. 15, Alley 11, Lane 100, Jiafeng 1st Street Zhubei City, Hsinchu County 302, Taiwan, R.O.C.
(9)	Chia-Shiung Tsai	of	No. 5, 50 Alley, 62 Lane, Gua-Tsuey Road Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

WAFER LEVEL PACKAGING BOND

for which we have executed an application for Letters Patent of the United States of America,

_______ of even date filed herewith; and
x filed on March 23, 2010, and assigned application no. 12/729,911 and;

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Martin Liu

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Yonghe City, Taipei County 234, Taiwan, R.O.C.

Dated: ✓ 2010. 3. 11.

✓
Inventor Signature

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Dated: 2010 03 11

Richard Chu
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Dated: 2010 03 11

Hung hua Lin
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Dated: 20100311

HT Huang
Inventor Signature

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Dated: 2010, 03 11

Jung-Huei Peng
Inventor Signature

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Dated: Mar. 16, 2010

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Dated: Mar 11, 2010

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Dated: Mar. 16, 2010

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Dated: 3. 16. 2010

Chia Shiung Tsai
Inventor Signature
